

C1206J225K3RACTU

Aliases (C1206J225K3RAC7800) SMD Comm X7R FO, Ceramic, 2.2 uF, 10%, 25 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 1206, 1.5 mm



Click here for the 3D model.

| General Information | |
|--------------------------|---|
| Series | SMD Comm X7R FO |
| Style | SMD Chip |
| Description | SMD, MLCC, Open Mode, Temperature Stable |
| Features | Open Mode, Temperature Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 41 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|--|
| Capacitance | 2.2 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 10% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 227.3 MOhms |

 Dimensions

 Chip Size
 1206

 L
 3.3mm +/-0.4mm

 W
 1.6mm +/-0.35mm

 T
 1.6mm +/-0.20mm

 S
 1.5mm MIN

 B
 0.6mm +/-0.25mm

Packaging Specifications

| Packaging | T&R, 180mm, Plastic Tape |
|--------------------|--------------------------|
| Packaging Quantity | 2000 |

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